

## GENERAL DESCRIPTION

This Trench MOSFET has better characteristics, such as fast switching time, low on resistance, low gate charge and excellent avalanche characteristics. It is mainly suitable for DC/DC Converters.

## FEATURES

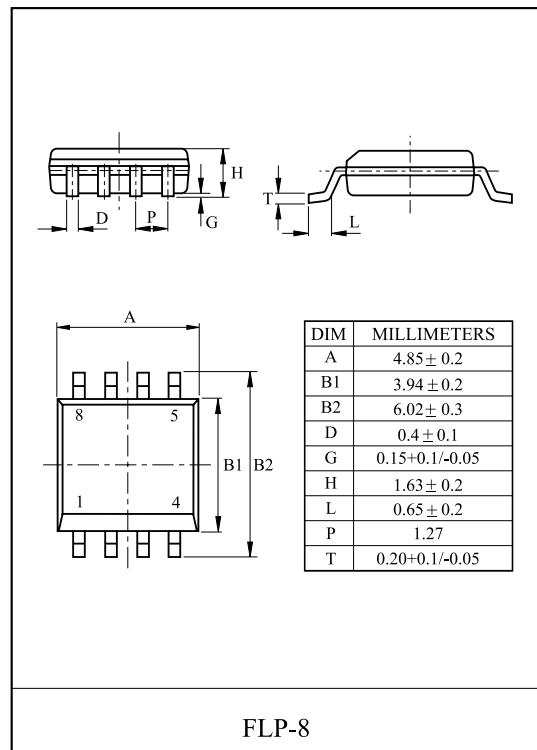
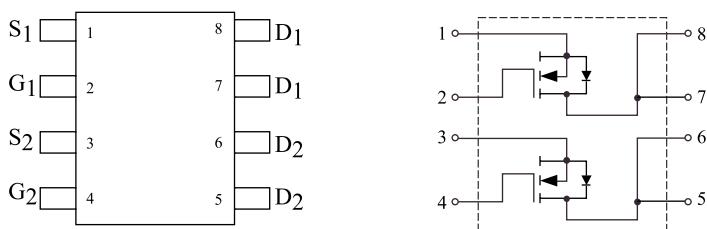
- $V_{DSS}=35V$ ,  $I_D=6A$ .
- Drain-Source ON Resistance.  
 $R_{DS(ON)}=28m\Omega$  (Max.) @  $V_{GS}=10V$   
 $R_{DS(ON)}=42m\Omega$  (Max.) @  $V_{GS}=4.5V$
- Super High Dense Cell Design
- Very fast switching

MAXIMUM RATING ( $T_a=25^\circ C$  Unless otherwise noted)

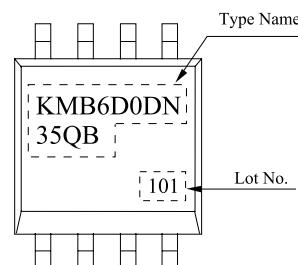
CHARACTERISTIC		SYMBOL	PATING	UNIT
Drain Source Voltage		$V_{DSS}$	35V	V
Gate Source Voltage		$V_{GSS}$	$\pm 20$	V
Drain Current	$T_a=25^\circ C$	$I_D$ *	6	A
	Pulsed(Note1)	$I_{DP}$	24	A
Drain Source Diode Forward Current		$I_S$	1.3	A
Drain Power Dissipation	$T_a=25^\circ C$	$P_D$ *	2	W
Maximum Junction Temperature		$T_j$	-50~150	
Storage Temperature Range		$T_{stg}$	-50~150	
Thermal Resistance, Junction to Ambient		$R_{thJA}$ *	62.5	/W

\* : Surface Mounted on FR4 Board (25mm x 25mm, 1.5t)

## PIN CONNECTION (TOP VIEW)



## Marking



# KMB6D0DN35QB

## ELECTRICAL CHARACTERISTICS (T<sub>j</sub>=25°C) UNLESS OTHERWISE NOTED

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
<b>Static</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	I <sub>D</sub> =250 μA, V <sub>GS</sub> =0V	35	-	-	V
Drain Cut-off Current	I <sub>DSS</sub>	V <sub>DS</sub> =35V, V <sub>GS</sub> =0V	-	-	1	μA
Gate Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	-	-	±100	nA
Gate Threshold Voltage	V <sub>th</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250 μA	1.0	2.0	3.0	V
Drain-Source ON Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10.0V, I <sub>D</sub> =6A	-	24	28	m
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =5A	-	35	42	
On-State Drain Current	I <sub>D(ON)</sub>	V <sub>DS</sub> =5V, V <sub>GS</sub> =10V	20	-	-	A
Forward Transconductance	g <sub>f</sub>	V <sub>DS</sub> =10V, I <sub>D</sub> =6A	-	20	-	S
<b>Dynamic</b>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =15V, f=1MHz, V <sub>GS</sub> =0V	-	460	-	pF
Output Capacitance	C <sub>oss</sub>		-	170	-	
Reverse Transfer Capacitance	C <sub>rss</sub>		-	50	-	
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =28V, V <sub>GS</sub> =10V, I <sub>D</sub> =6A (Note2,3)	-	9.0	12.6	nC
Gate-Source Charge	Q <sub>gs</sub>		-	1.5	-	
Gate-Drain Charge	Q <sub>gd</sub>		-	3.0	-	
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =28V, V <sub>GS</sub> =5V, I <sub>D</sub> =6A (Note2,3)	-	5.5	-	
Turn-On Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> =15V, V <sub>GS</sub> =10V I <sub>D</sub> =1A, R <sub>G</sub> =6Ω (Note2,3)	-	16	-	ns
Turn-On Rise Time	t <sub>r</sub>		-	14.5	25.5	
Turn-Off Delay Time	t <sub>d(off)</sub>		-	40	-	
Turn-Off Fall Time	t <sub>f</sub>		-	11.5	21	
<b>Source-Drain Diode Ratings</b>						
Source-Drain Forward Voltage	V <sub>SDF</sub>	I <sub>DR</sub> =1.7A, V <sub>GS</sub> =0V	-	0.75	1.2	V

Note1) Repetivity rating : Pulse width Limited by junction temperature.

Note2) Pulse test : Pulse width 300μs, Duty cycle 2%

Note3) Essentially independent of operating temperature.

# KMB6D0DN35QB

Fig1.  $I_D$  -  $V_{DS}$

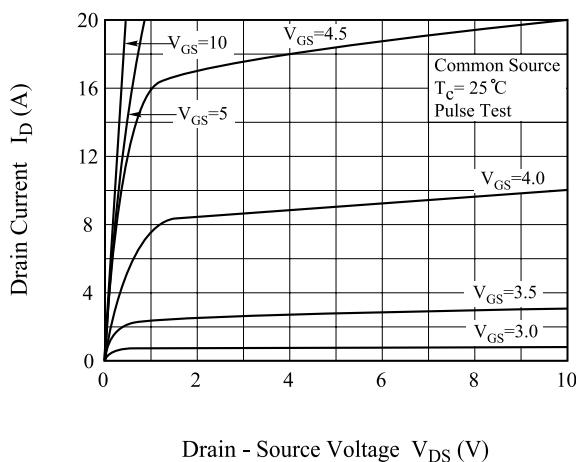


Fig2.  $R_{DS(on)}$  -  $I_D$

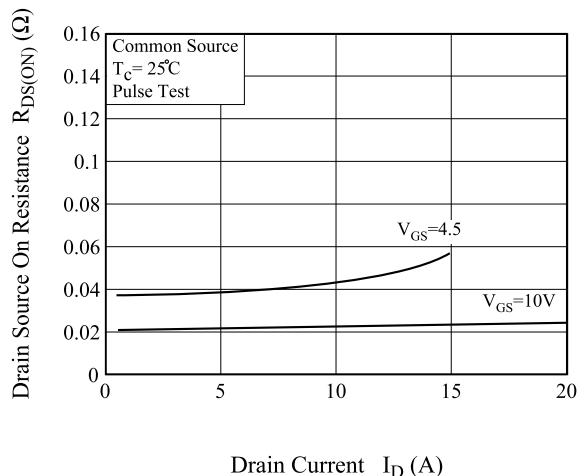


Fig3.  $I_D$  -  $V_{GS}$

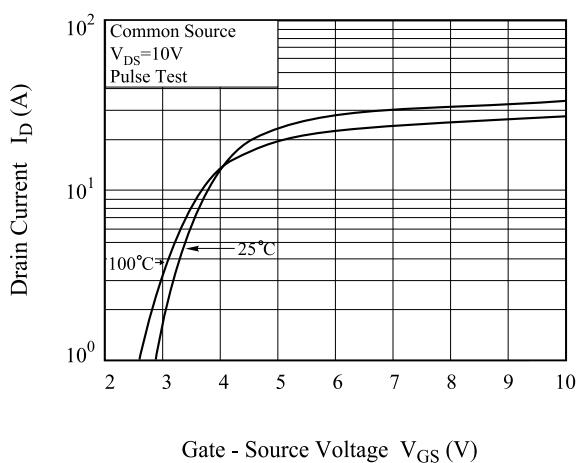


Fig4.  $R_{DS(on)}$  -  $T_j$

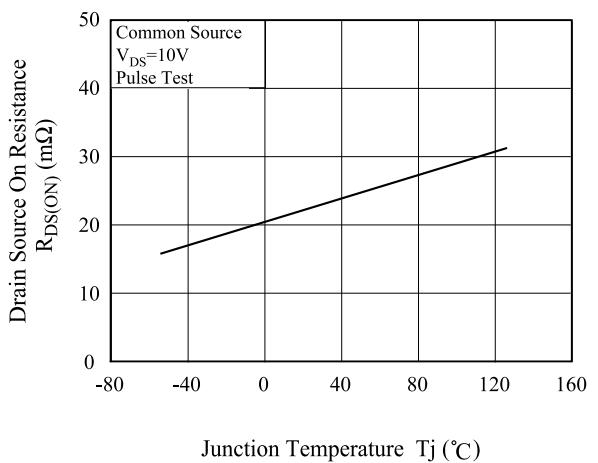


Fig5.  $V_{th}$  -  $T_j$

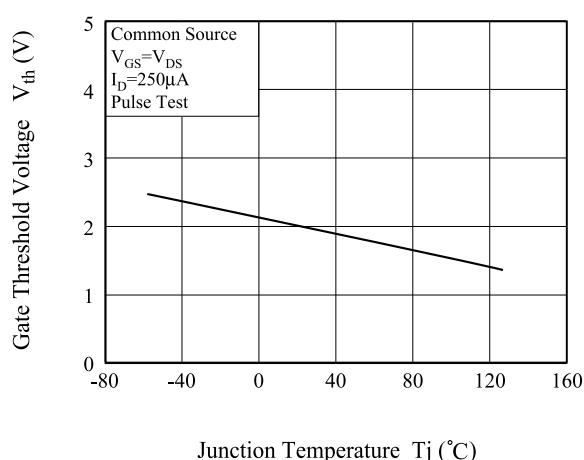
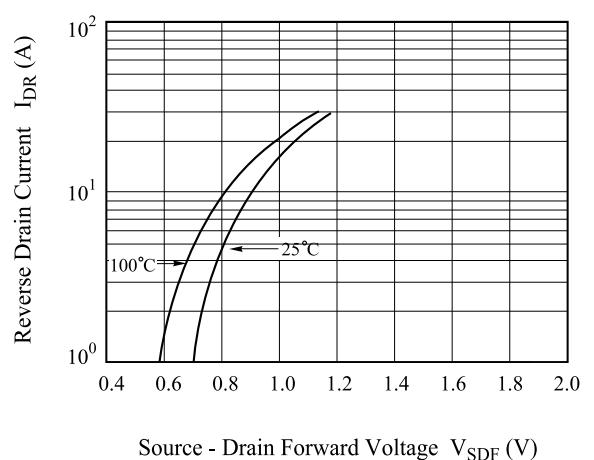


Fig6.  $I_{DR}$  -  $V_{SDF}$



# KMB6D0DN35QB

Fig7. Qg - V<sub>GS</sub>

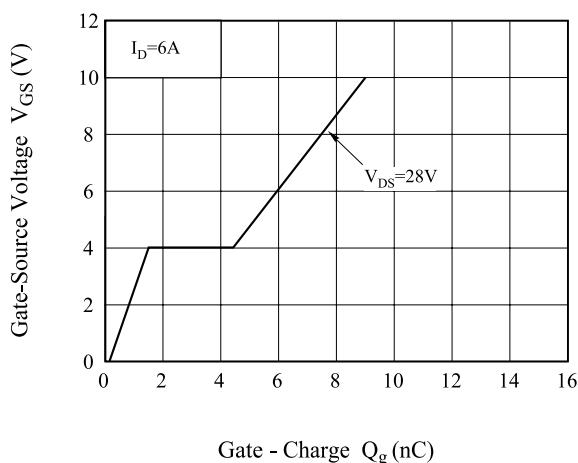


Fig8. Safe Operation Area

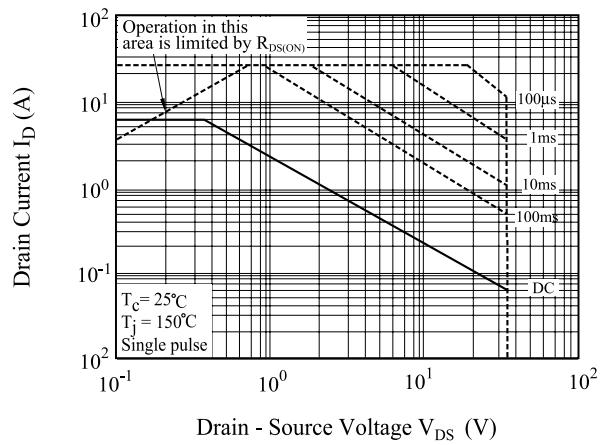
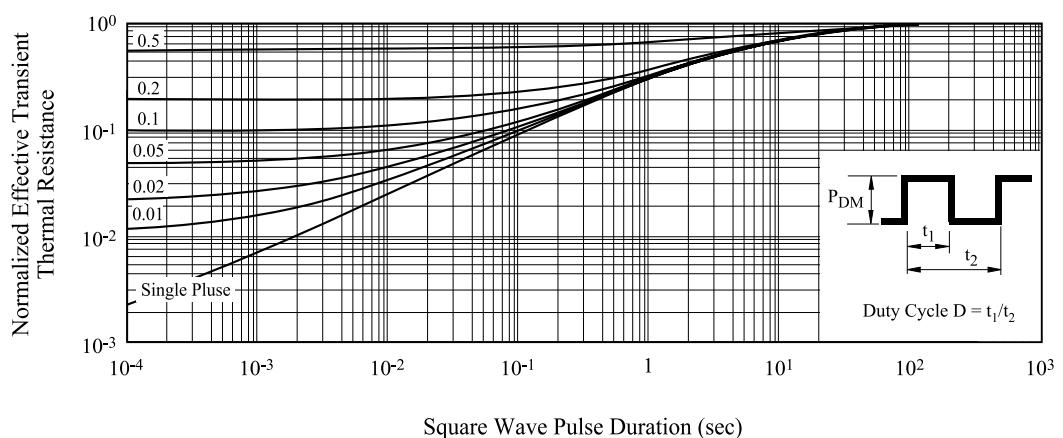


Fig9. Transient Thermal Response Curve



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Fig. 10 Gate Charge

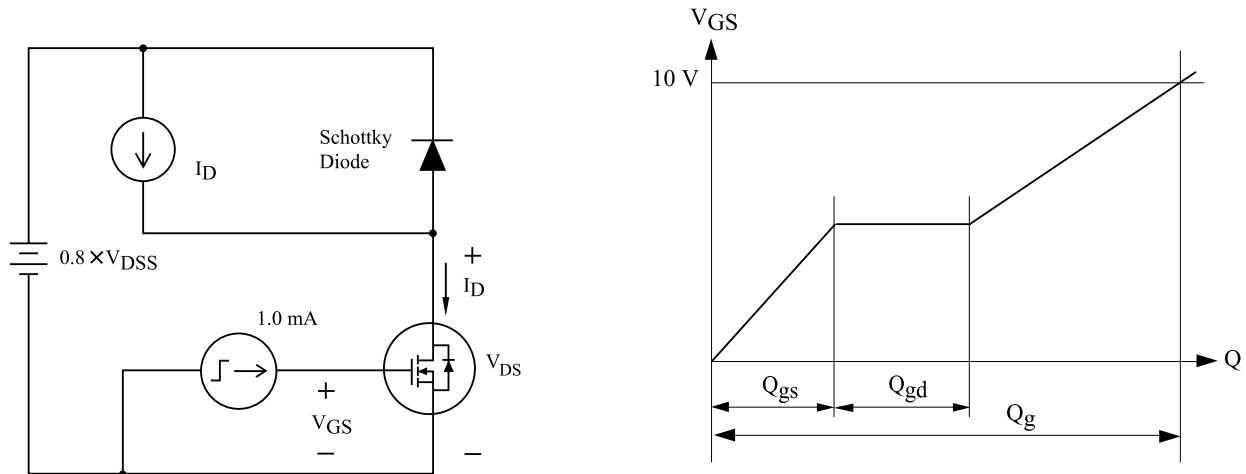


Fig. 11 Resistive Load Switching

